

Schottky Diode

High Performance Schottky Diode Low Loss and Soft Recovery Single Diode

Part number

DSS25-0025B



 $V_{RRM} = 25 V$ $I_{FAV} = 25 A$ $V_{F} = 0.45 V$



Backside: cathode

Features / Advantages:

- Very low Vf
- Extremely low switching losses
- low Irm values
- Improved thermal behaviour
- High reliability circuit operation
- Low voltage peaks for reduced protection circuits
- Low noise switching

Applications:

- Rectifiers in switch mode power supplies (SMPS)
- Free wheeling diode in low voltage converters

Package:

- Housing: TO-220
- Industry standard outline
- Epoxy meets UL 94V-0
- RoHS compliant

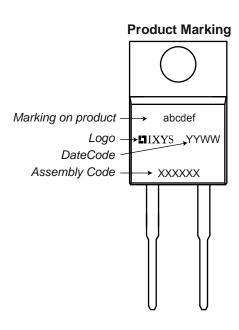
Ratings

Symbol	Definition	Conditions		min.	typ.	max.	Unit
V_{RRM}	max. repetitive reverse voltage		T _{VJ} = 25°C			25	V
I _R	reverse current	V _R = 25 V	$T_{VJ} = 25^{\circ}C$			20	mA
		$V_R = 25 V$	$T_{VJ} = 100$ °C			80	mA
V _F	forward voltage	I _F = 25A	$T_{VJ} = 25^{\circ}C$			0.52	V
		$I_F = 50 A$				0.67	V
		I _F = 25A	T _{VJ} = 125°C			0.45	V
		$I_F = 50 A$				0.66	V
I _{FAV}	average forward current	rectangular, d = 0.5	$T_c = 125$ °C			25	Α
V _{F0}	threshold voltage		T _{VJ} = 150°C			0.21	V
r _F	slope resistance					8.8	mΩ
R_{thJC}	thermal resistance junction to case					1.40	K/W
T _{VJ}	virtual junction temperature			-55		150	°C
P _{tot}	total power dissipation		$T_{c} = 25^{\circ}C$			90	W
I _{FSM}	max. forward surge current	t = 10 ms (50 Hz), sine	$T_{VJ} = 45^{\circ}C$			330	Α
E _{AS}	non-repetitive avalanche energy	I _{AS} = 20 A; L = 100 μH	$T_{VJ} = 25^{\circ}C$			20	mJ
I _{AR}	repetitive avalanche current	$V_A = 1.5 \cdot V_R \text{ typ.; } f = 10 \text{ kHz}$				2	Α



				Ratings				
Symbol	Definition	Conditions	min.	typ.	max.	Unit		
I _{RMS}	RMS current	per pin ¹⁾			35	Α		
R _{thCH}	thermal resistance case to heatsink			0.50		K/W		
T _{stg}	storage temperature		-55		150	°C		
Weight				2		g		
M _D	mounting torque		0.4		0.8	Nm		
F _c	mounting force with clip		20		60	N		

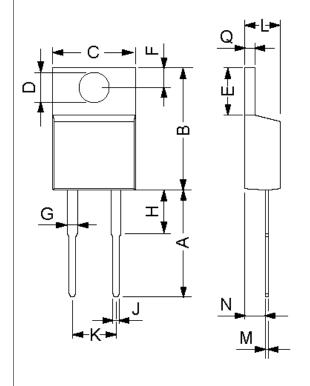
¹⁾ I_{RMS} is typically limited by: 1. pin-to-chip resistance; or by 2. current capability of the chip. In case of 1, a common cathode/anode configuration and a non-isolated backside, the whole current capability can be used by connecting the backside.



Ordering	Part Name	Marking on Product	Delivering Mode	Base Qty	Code Key
Standard	DSS25-0025B	DSS25-0025B	Tube	50	475114



Outlines TO-220



Dim.	Millimeter		Inches		
Dilli.	Min.	Max.	Min.	Max.	
Α	12.7	14.73	0.5	0.58	
В	14.23	16.51	0.56	0.65	
С	9.66	10.66	0.38	0.42	
D	3.54	4.08	0.139	0.161	
E	5.85	6.85	2.3	0.42	
F	2.54	3.42	0.1	0.135	
G	1.15	1.77	0.045	0.07	
Н	-	6.35	-	0.25	
J	0.64	0.89	0.025	0.035	
K	4.83	5.33	0.19	0.21	
L	3.56	4.82	0.14	0.19	
М	0.51	0.76	0.02	0.03	
N	2.04	2.49	0.08	0.115	
Q	0.64	1.39	0.025	0.055	



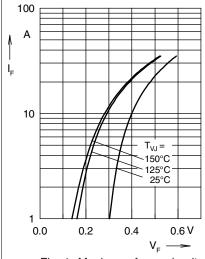


Fig. 1 Maximum forward voltage drop characteristics

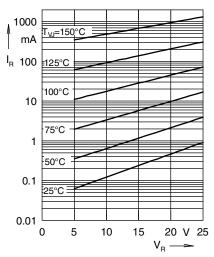


Fig. 2 Typ. value of reverse current $I_{\mbox{\tiny R}}$ vs. reverse voltage $V_{\mbox{\tiny R}}$

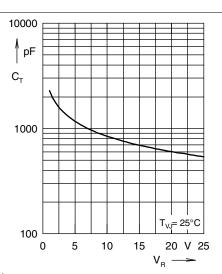


Fig. 3 Typ. junction capacitance C_T vs. reverse voltage V_R

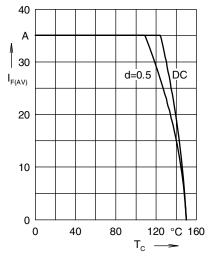


Fig. 4 Avg. forward current $I_{\text{F(AV)}}$ vs. case temperature T_{C}

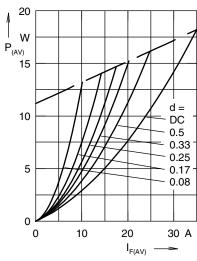


Fig. 5 Forward power loss characteristics

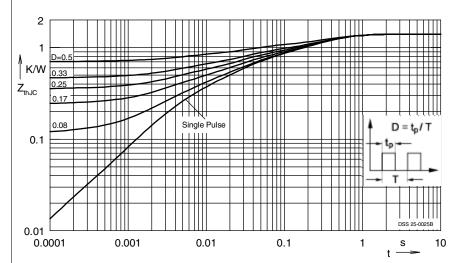


Fig. 6 Transient thermal impedance junction to case at various duty cycles

Note: All curves are per diode